

SE2101

P-Channel Enhancement-Mode MOSFET

Revision: A

General Description

This type is P-Channel enhancement mode power MOSFET which is produced with high cell density and DMOS trench technology. This device particularly suits low voltage applications, especially for battery powered circuits.

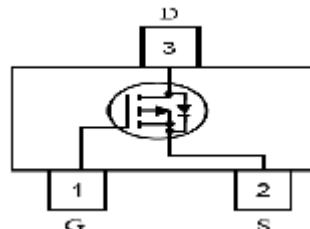
Features

For a single MOSFET

- $V_{DS} = -20V$
- $I_D = -0.9A$
- $R_{DS(ON)} = 280m\Omega @ V_{GS}=-4.5V$
- $R_{DS(ON)} = 370m\Omega @ V_{GS}=-2.5V$

Pin configurations

See Diagram below



SOT-23

Absolute Maximum Ratings

Parameter		Symbol	Rating	Units
Drain-Source Voltage		V_{DS}	-20	V
Gate-Source Voltage		V_{GS}	± 12	V
Drain Current	Continuous	I_D	-0.9	A
	Pulsed		-3	
Total Power Dissipation	@ $T_A=25^\circ C$	P_D	250	mW
Operating Junction Temperature Range		T_J	-55 to 150	°C

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Electrical Characteristics (TJ=25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS (Note 2)						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0 V	-20			V
I _{DSS}	Drain to Source Leakage Current	V _{DS} = -16V, V _{GS} =0V			-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = 12V			10	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =-250μA	-0.35	-0.6	-1	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-4.5V, I _D =-1A		280	300	mΩ
		V _{GS} =-2.5V, I _D =-0.5A		370	400	
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-6V, f=200KHz		200		pF
C _{oss}	Output Capacitance			80		pF
C _{rss}	Reverse Transfer Capacitance			150		pF
SWITCHING PARAMETERS						
t _{d(on)}	Turn-On Delay Time	V _{GS} =-4.5V, V _{DS} =-6V, R _{GEN} =6Ω, I _D =-1A		10		ns
t _{d(off)}	Turn-Off Delay Time			19		ns
t _{d(r)}	Turn-On Rise Time			62		ns
t _{d(f)}	Turn-Off Fall Time			18		ns
Thermal Resistance						
Symbol	Parameter		Typ	Max	Units	
R _{θJC}	Junction to Case		6.9	8	°C/W	
R _{θJA}	Junction to Ambient (t ≤ 10s)		52	62.5	°C/W	

Typical Characteristics

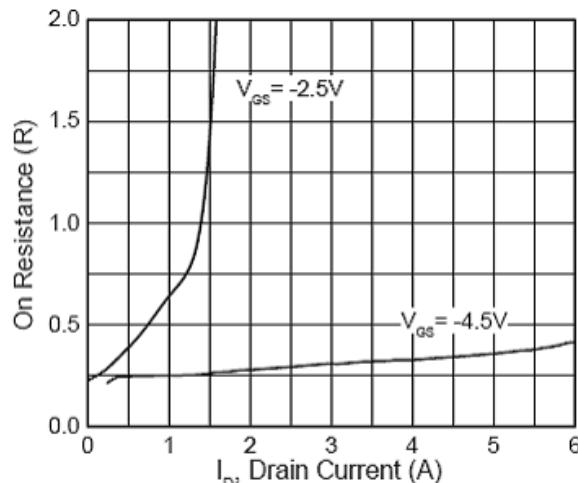


Figure 3. On Resistance VS I_D

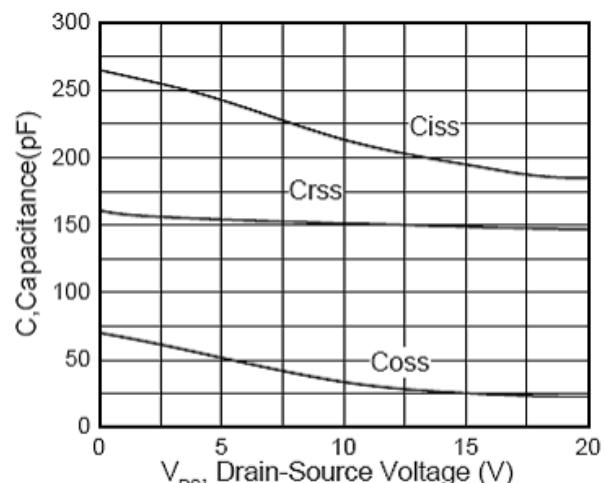


Figure 4. Capacitance

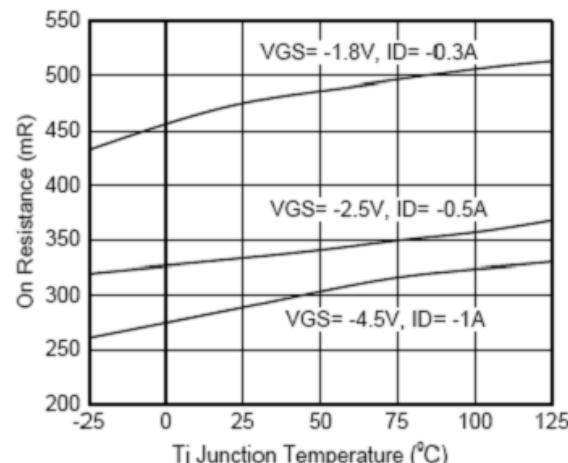


Figure 5 . On resistance VS Temperature

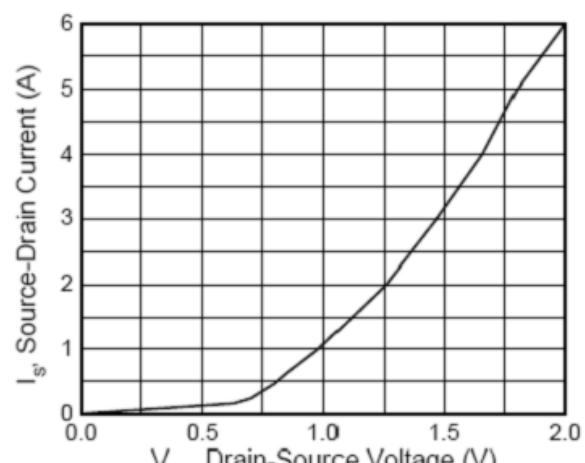


Figure 6. V_{SD} VS I_s

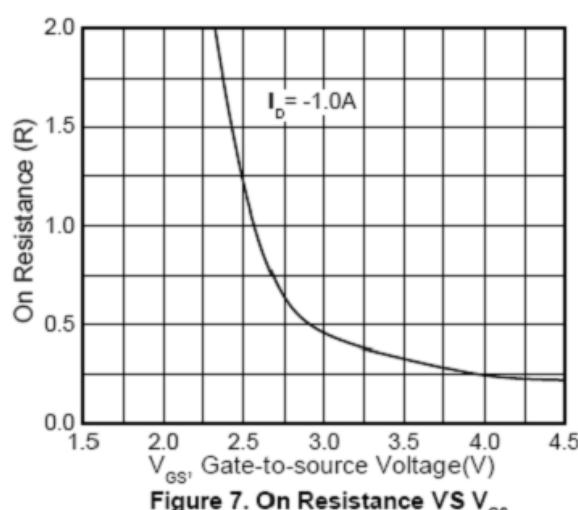


Figure 7. On Resistance VS V_{GS}

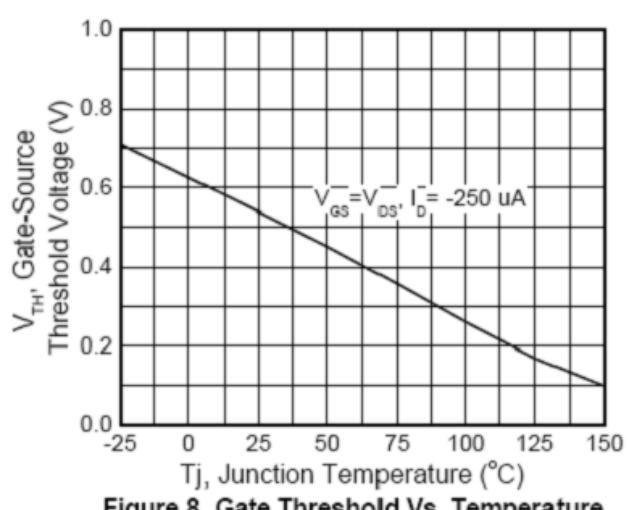
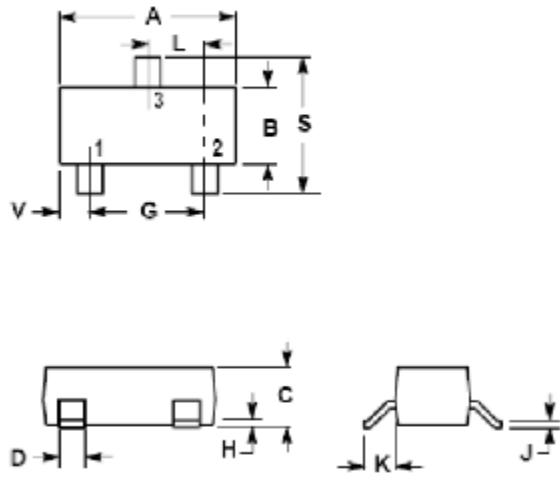


Figure 8. Gate Threshold Vs. Temperature

Package Outline Dimension

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NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.1102	0.1197	2.80	3.04
B	0.0472	0.0551	1.20	1.40
C	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
H	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.086	0.177
K	0.0140	0.0285	0.36	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
V	0.0177	0.0236	0.45	0.60

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